

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		User Part Number						
		HPZR-C60-Q						
		Part Description						
		Nexperia DHAM	Zener					
		SMD package						
		Test Conditions	Duration	# Lots	# Quantity	# Rejects		
	TEST Pre- and Post-Stress							
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below		
# A1	PC Preconditioning	JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Reflow soldering	24 hours 168 hours 3 cycles	1514	64430	0		
	HTRB High Temperature Reverse	MIL-STD-750-1 M1038 Method A Tj = Tjmax, VR = 80 % of rated reverse	·					
# B1 # B1b	SSOP Steady State Operational	voltage MIL-STD-750-1 M1038 Method B Tj = Tjmax, Iz = 100% of max. datasheet reverse current	1000 hours	250	11400	0		
# A4	TC Temperature Cycling	JESD22-A104 -65 °C to Tjmax, not to exceed 150°C	1000 cycles	311	14080	0		
# A3 or	UHAST Unbiased HAST	JESD22-A118 Tamb = 130 °C, RH = 85 %	—96 hours	311	14080	0		
# A3 alt	AC Autoclave	JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)						
	H3TRB High Humidity High	JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of						
# A2 alt	, , , , , , , , , , , , , , , , , , ,	rated reverse voltage ^[1] MIL-STD-750 Method 1037	1000 hours	311	14080	0		
# A5	IOL Intermittent Operating Life	ton = toff, devices powered to insure ΔTj = 100 °C for 15000 cycles	1000 hours	312	14120	0		
# C8	RSH Resistance to Solder Heat	JESD22-A111 260 °C ± 5 °C	10 s	269	8070	0		
# C10	SD Solderability	J-STD-002		19	6660	0		

^[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Zener	11400	0	0,37	2,68E+09

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